

Application Specific Discretes A.S.D.™

ESDA6V1-5W6

TRANSIL™ ARRAY FOR ESD PROTECTION

APPLICATIONS

Where transient overvoltage protection in ESD sensitive equipment is required, such as:

- Computers
- Printers
- Communication systems
- Cellular phone handsets and accessories
- Other telephone sets
- Set top boxes



The ESDA6V1-5W6 is a 5-bit wide monolithic suppressor which is designed to protect components connected to data and transmission lines against ESD.

FEATURES

- 5 UNIDIRECTIONAL TRANSIL™ FUNCTIONS
- BREAKDOWN VOLTAGE: VBR = 6.1V min
- LOW LEAKAGE CURRENT: I_R max < 1 μA
- VERY SMALL SIZE FOR PCB SPACE SAVING: 4.2mm² TYPICALLY

BENEFITS

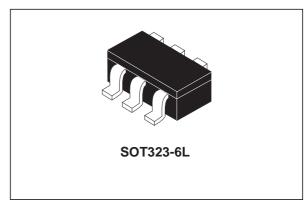
- High integration
- Suitable for high density boards

COMPLIES WITH THE FOLLOWING STANDARDS:

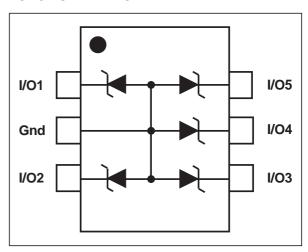
- IEC 61000-4-2: level 4

15 kV (air discharge) 8 kV (contact discharge)

- MIL STD 883C-Method 3015-6: class3 (human body model)

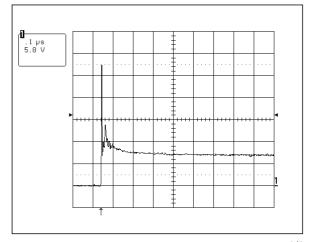


FUNCTIONAL DIAGRAM



ESD response to IEC61000-4-2

(air discharge 16kV, positive surge)



March 2000 - Ed: 1A 1/9

ESDA6V1-5W6

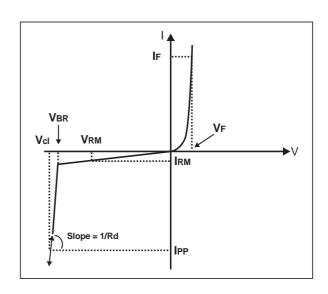
ABSOLUTE MAXIMUM RATINGS $(T_{amb} = 25^{\circ}C)$

Symbol	Test conditions	Value	Unit
V _{PP}	ESD discharge - MIL STD 883C - Method 3015-6 IEC 61000-4-2 air discharge IEC 61000-4-2 contact discharge	25 20 15	kV
P _{PP}	Peak pulse power (8/20μs)	100	W
Tj	Junction temperature	150	°C
T _{stg}	Storage temperature range	-55 to +150	°C
TL	Lead solder temperature (10 seconds duration)	260	°C
T _{op}	Operating temperature range (note 1)	-40 to +125	°C

 $\textbf{Note 1}: The \ evolution \ of \ the \ operating \ parameters \ versus \ temperature \ is \ given \ by \ curves \ and \ \alpha T \ parameter.$

ELECTRICAL CHARACTERISTICS (T_{amb} = 25°C)

Symbol	Parameter			
V _{RM}	Stand-off voltage			
V _{BR}	Breakdown voltage			
V _{CL}	Clamping voltage			
I _{RM}	Leakage current			
I _{PP}	Peak pulse current			
αΤ	Voltage temperature coefficient			
С	Capacitance			
Rd	Dynamic impedance			
V _F	Forward voltage drop			



	V _{BR} @ I _R		I _{RM} @ V _{RM}		Rd	αΤ	С	V _F @ I _F		
	min.	max		max.		typ.	max.	typ.	max	
Туре						note 2	note 3	0V bias		
	V	V	mA	μΑ	V	mΩ	10 ⁻⁴ /°C	рF	V	mA
ESDA6V1-5W6	6.1	7.2	1	1	3	610	6	50	1.25	200

Note 2 : Square pulse, Ipp = 15A, tp= $2.5\mu s$.

Note 3: $\Delta V_{BR} = \alpha T * (T_{amb} - 25 °C) * V_{BR} (25 °C)$

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Fig. 1: Peak power dissipation versus initial junction temperature.

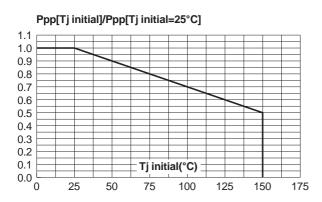


Fig. 3: Clamping voltage versus peak pulse current (Tj initial = 25°C) Rectangular waveform tp = 2.5µs.

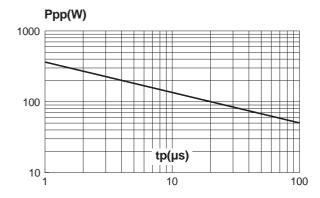


Fig. 2: Peak pulse power versus exponential

pulse duration (Tj initial = 25°C).

Fig. 4: Capacitance versus reverse applied voltage (typical values).

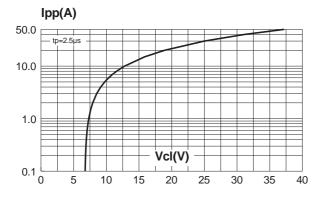


Fig. 5: Relative variation of leakage current versus junction temperature (typical values).

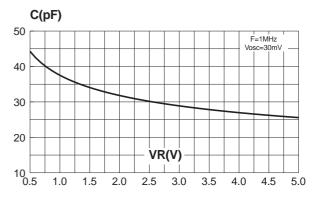
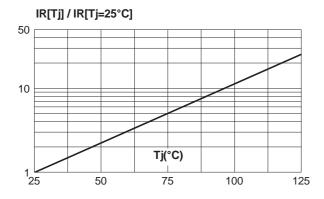
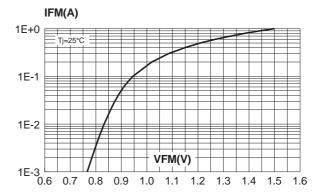


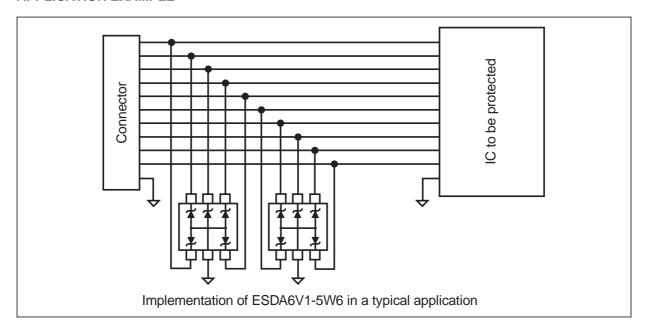
Fig. 6: Peak forward voltage drop versus peak forward current (typical values).





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APPLICATION EXAMPLE



TECHNICAL INFORMATION

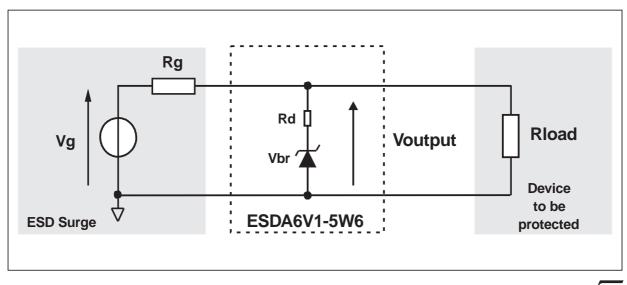
ESD PROTECTION

The **ESDA6V1-5W6** is particularly optimized to perform ESD protection. ESD protection is achieved by clamping the unwanted overvoltage. The clamping voltage is given by the following formula:

$$V_{cl} = V_{br} + R_d \cdot I_{pp}$$

As shown in figure A1, the ESD strikes are clamped by the transient voltage suppressor.

Fig. A1: ESD clamping behavior



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To have a good approximation of the remaining voltages at both Vi/o side, we provide the typical dynamical resistance value Rd. By taking into account the following hypothesis:

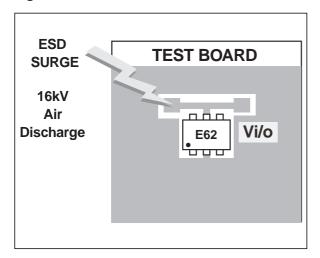
we have:

$$Vin = V_{br} + R_d \times \frac{V_g}{R_g}$$

The results of the calculation done for Vg = 8 kV, Rg = 330 Ω (IEC 61000-4-2 standard), Vbr = 6.4 V (typ.) and Rd = 0.61 Ω (typ.) give:

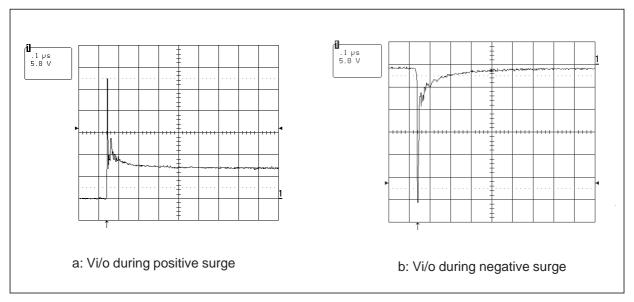
This confirms the very low remaining voltage across the device to be protected. It is also important to note that in this approximation the parasitic inductance effect was not taken into account. This could be a few tenths of volts during a few ns at the Vi/o side.

Fig. A2: Measurement conditions:



The measurements done here after show very clearly (Fig. A3) the high efficiency of the ESD protection: the clamping voltage Vout becomes very close to Vbr (positive way, Fig. A3a) and -Vf (negative way, Fig. A3b).

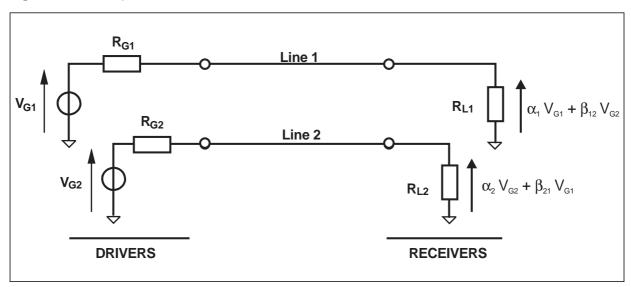
Fig. A3: Remaining voltage during ESD surge



One can note that the **ESDA6V1-5W6** is not only acting for positive ESD surges but also for negative ones. For these kind of disturbances it clamps close to ground voltage as shown in Fig. A3b.

CROSSTALK BEHAVIOR

Fig. A4: Crosstalk phenomenon



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The crosstalk phenomena are due to the coupling between 2 lines. The coupling factor (β_{12} or β_{21}) increases when the gap across lines decreases, particularly in silicon dice. In the example above the expected signal on load R_{L2} is $\alpha_2 V_{G1}$. In fact the real voltage at this point has got an extra value $\beta_{21} V_{G1}$. This part of the V_{G1} signal represents the effect of the crosstalk phenomenon of the line 1 on the line 2. This phenomenon has to be taken into account when the drivers impose fast digital data or high frequency analog signals in the disturbing line. The perturbed line will be more affected if it works with low voltage signal or high load impedance (few $k\Omega$).

Fig. A5: Analog crosstalk measurements

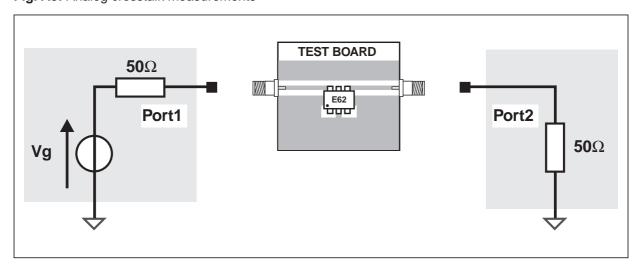


Fig. A6: Typical analog crosstalk measurements

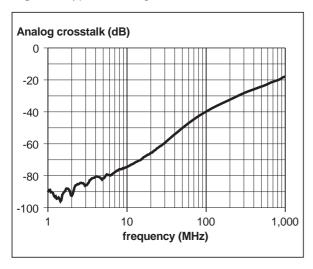


Figure A5 gives the measurement circuit for the analog crosstalk application. In figure A6, the curve shows the effect of the cell I/O5 on the cell I/O3. In usual frequency range of analog signals (up to 100MHz) the effect on disturbed line is less than -40dB.

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Fig. A7: Digital crosstalk measurements configuration

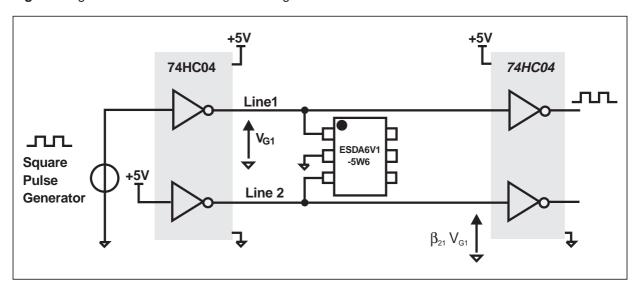


Fig. A8: Digital crosstalk measurements configuration

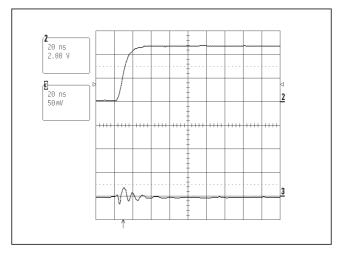
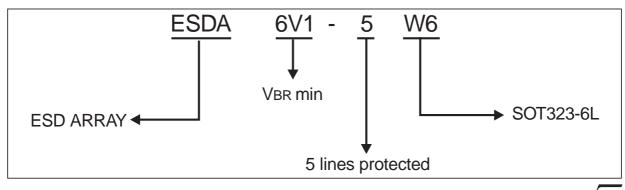


Figure A7 shows the measurement circuit used to quantify the crosstalk effect in a classical digital application.

Figure A8 shows that in such a condition, i.e signal from 0 to 5V and rise time of a few ns, the impact on the disturbed line is less than 50 mV peak to peak. No data disturbance was noted on the concerned line. The measurements performed with falling edges give an impact within the same range.

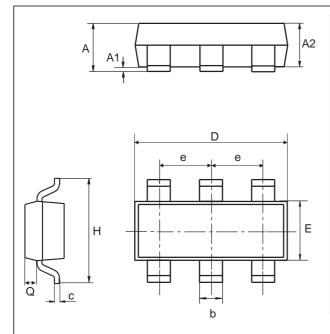
ORDER CODE



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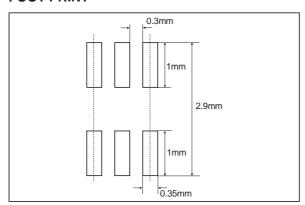
PACKAGE MECHANICAL DATA

SOT323-6L



	DIMENSIONS						
REF.	Millim	neters	Inches				
	Min.	Max.	Min.	Max.			
Α	0.8	1.1	0.031	0.043			
A1	0	0.1	0	0.004			
A2	0.8	1	0.031	0.039			
b	0.15	0.3	0.006	0.012			
С	0.1	0.18	0.004	0.007			
D	1.8	2.2	0.071	0.086			
E	1.15	1.35	0.045	0.053			
е	0.65	Тур.	0.025 Typ.				
Н	1.8	2.4	0.071	0.094			
Q	0.1	0.4	0.004	0.016			

FOOT PRINT



MARKING

Туре	Marking	Package	Weight	Base Qty	Delivery mode
ESDA6V1-5W6	E62	SOT323-6L	5.4 mg	3000	Tape & Reel

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